

Call for Papers

Special Issue on “Flexible electronics for emerging markets and developing economies”

IEEE Journal on Flexible Electronics (JFLEX) provides an excellent platform to share progress in state-of-the-art research and innovations in the area of flexible electronics. Flexible Electronics is a comparatively fledgling technology area and it is important to harness its potential effectively to address human needs in optimum ways. Important application spaces of this disruptive technology are likely to be in today’s emerging and developing economies of the world – which encompasses nearly 80% of the countries and more than 85% of world’s population. In the coming decades, most of the economic growth is predicted to be in emerging and developing economies. In view of that, it should be pertinent to initiate efforts to tap into the ideas that are pertaining to these markets and involve those working on them by JFLEX.

Submissions of papers from anywhere in the world with higher technology readiness level (TRL) applications for emerging markets and developing economies will be preferred. Besides, research papers in any area of flexible electronics or allied areas - molecules, materials, fabrications steps, devices, circuits, systems, applications and challenges to commercialisation of products – which have at least one of the authors working in academic institutions, government research labs and industries in countries with emerging markets and developing economies, are within the scope of the proposed special journal issue. Results from multinational collaborations between researchers across countries (including those from developed countries) are welcome to be submitted for being considered in the special issue.

Topics

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| - Novel applications of flexible electronics technology | Flexible/Printable Electronics in context with Circular Economy | - Printable displays, lighting sources Packaging |
| - Stretchable/Shrinkable Sensors and Electronics | - Organic/Inorganic/Hybrid Flexible Sensors and Electronics | - Modeling of printable sensors |
| - Hybrid Systems-in-Foil | - Printable batteries, energy harvesters | - Manufacturing Techniques (including Printing) |
| - Biomedical sensing devices | - Wearable sensors | - Emerging Materials for Flexible and Printable Systems |
| - Electronic textile/paper/skin | - Sensors for health monitoring | - 3D printing |
| - Smart tags, RFID tags, etc. | | |

Important dates (tentative)

August 2022:	Call for Papers (to appear in IEEE Journal on Flexible Electronics)
December, 2022:	Deadline for Paper Submission
February, 2023:	Completion of First Review
March, 2023:	Completion of Final Review
May, 2023:	Publication

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Submission and Peer Review of Papers

All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the *IEEE Manuscript Central*TM, see <https://mc.manuscriptcentral.com/jflex>. When submitting, please indicate in the “Manuscript Type” roll down menu, and also by e-mail to John Wright, john.wright@ieee.org, that the paper is intended for the “Flexible electronics for emerging markets and developing economies” Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central*. For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE J-FLEX web page, <https://ieee-jflex.org/guidelines-for-authors/>.